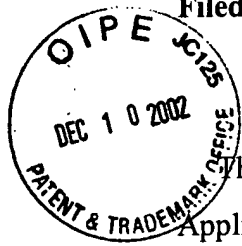


Appl. No.
Filed

: 09/9987,232
: November 6, 2001



VERSION WITH MARKINGS TO SHOW CHANGES MADE

This application is related to and claims the benefit of the filing of U.S. Provisional Application No. 60/331,021, entitled Thermoelectric Hetrostructure Assemblies Element, filed October 24, 2001.

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